

PTO-1594

RECORDATION FORM COVER SHEET  
TRADEMARKS ONLY

U.S. DEPARTMENT OF COMMERCE  
U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 6/30/2005)

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Gould Electronics Inc.  
35129 Curtis Boulevard  
Eastlake, Ohio 44095

- Individual(s)
- General Partnership
- Corporation-State
- Other
- Association
- Limited Partnership

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

- Assignment
- Security Agreement
- Other Bill of Sale and Instrument
- Merger
- Change of Name

Execution Date: 09/30/2003  
of Assignment and Assumption

2. Name and address of receiving party(ies)

Name: Nikko Materials USA, Inc.  
Internal Address: \_\_\_\_\_  
Address: \_\_\_\_\_  
Street Address: 125 North Price Road  
City: Chandler State: AZ Zip: 85224

- Individual(s) citizenship
- Association
- General Partnership
- Limited Partnership
- Corporation-State Arizona
- Other

If assignee is not domiciled in the United States, a domestic representative designation is attached:  Yes  No  
(Designations must be a separate document from assignment)  
Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or registration number(s):

A. Trademark Application No.(s) \_\_\_\_\_

B. Trademark Registration No.(s) 1800591; 2368020;  
1267714; 1519518; 1271536; 635119;

Additional number(s) attached  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Debra L. Pejeau  
Internal Address: Jones Day  
North Point

Street Address: 901 Lakeside Avenue  
City: Cleveland State: OH Zip: 44114

6. Total number of applications and registrations involved:

**16**

7. Total fee (37 CFR 3.41).....\$ 415.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

501432 (332100560007)

DO NOT USE THIS SPACE

9. Signature.

Debra L. Pejeau  
Name of Person Signing

Debra L. Pejeau  
Signature

10/01/2003  
Date

**13**

Total number of pages including cover sheet, attachments, and document:

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patent & Trademarks, Box Assignments  
Washington, D.C. 20231

CH \$415.00 501432 1800591

Recordation Form Cover Sheet - continued  
Attorney Docket No.: 332100560007

Continuation of Item 4.

2376973  
2127029  
1356346  
1020371  
2556738  
2687406  
2687405  
2687404  
2687403  
2762872

## **BILL OF SALE AND INSTRUMENT OF ASSIGNMENT AND ASSUMPTION**

THIS BILL OF SALE AND INSTRUMENT OF ASSIGNMENT AND ASSUMPTION (this "*Instrument*"), dated September 30, 2003, is made by and between GOULD ELECTRONICS INC., an Ohio corporation ("*Gould*") and NIKKO MATERIALS USA, INC., an Arizona corporation ("*Buyer*"). Capitalized terms used but not defined herein have the meanings ascribed to such terms in the Asset Purchase Agreement (as defined below).

### **BACKGROUND INFORMATION**

A. Japan Energy Electronic Materials, Inc. (f/k/a Japan Energy Corporation) ("*JEEM*"), a Japanese corporation, Gould and Buyer have determined that it is advisable and in the best interest of the parties to restructure Gould and its U.S. and non-U.S. subsidiaries to, among other things, (i) coordinate the operating structure of Gould's various businesses and (ii) enhance economic efficiencies and improve the strength of such businesses (the "*Restructuring*").

B. Pursuant to the Restructuring, and as part of the Restructuring, Buyer and Gould have entered into a definitive asset purchase agreement, dated of even date herewith (as amended, restated, supplemented or otherwise modified from time to time, the "*Asset Purchase Agreement*") pursuant to which Buyer has agreed to (i) purchase from Gould substantially all of the properties and assets of Gould, including, without limitation, all capital stock and other equity interests held by Gould, and (ii) assume all liabilities and obligations of Gould, other than all third party and certain affiliate indebtedness of Gould for borrowed money (including interest accrued thereon) and certain indebtedness for borrowed money (including interest accrued thereon) of Gould payable to JEEM (the "*Gould Asset Transfer*").

C. Pursuant to the Restructuring, and as part of the Restructuring, upon the consummation of the Gould Asset Transfer, Gould will (i) enter into and adopt an agreement and plan of liquidation and, in accordance with the requirements of the Ohio General Corporation Law, (ii) on or before March 31, 2004, file a certificate of dissolution with the Secretary of State of the State of Ohio, and (iii) on or before March 31, 2004, wind-up the remainder of its affairs and cease to conduct business.

### **STATEMENT OF AGREEMENT**

NOW, THEREFORE, in consideration of the foregoing premises and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Gould and Buyer hereby agree as follows:

1. Upon the terms and subject to the conditions set forth in the Asset Purchase Agreement, Gould hereby sells, conveys, assigns, transfers and delivers to Buyer all of Gould's right, title and interest in, to and under the Gould Acquired Assets, which include, without limitation the Patents and Trademarks listed on Attachment I hereto.

2. Upon the terms and subject to the conditions set forth in the Asset Purchase Agreement, Buyer hereby assumes all of the Gould Assumed Liabilities. Notwithstanding anything to the contrary herein, Buyer does not hereby assume any of the Gould Excluded Liabilities.

3. At the request and sole expense of the requesting party, Buyer or Gould, as applicable, shall execute and deliver, or cause to be executed and delivered, such documents as Buyer or Gould, as applicable, may reasonably request to effectuate the purposes of the Asset Purchase Agreement and this Instrument.

4. The validity, interpretation and effect of this Instrument shall be construed, performed and enforced in accordance with, and governed by, the internal laws of the State of Ohio, without giving effect to the principles of conflicts of law thereof.

5. This Instrument shall bind and shall inure to the benefit of the respective parties hereto and to their respective successors and permitted assigns.

6. This Instrument may be executed in counterparts, including by facsimile transmission or other electronic transmission capable of authentication, each of which shall be deemed an original, but all of which together constitute the same Instrument.

**[Signatures On Following Page]**

**ATTACHMENT I**

**Patents and Trademarks**

See Attached

IN WITNESS WHEREOF, the parties hereto have caused this Instrument to be  
by their authorized representatives.

**GOULD ELECTRONICS INC.**

By: Thomas N. Reich  
Name:  
Title:

**NIKKO MATERIALS USA, INC.**

By: [Signature]  
Name:  
Title

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**Gould Electronics Inc. U.S. Patents**


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**Country:** United States of America

<b>Patent No.</b>	<b>Title</b>	<b>Issue Date</b>
4490218	PROCESS AND APPARATUS FOR PRODUCING SURFACE TREATED METAL FOIL	25-Dec-1984
4529486	ANODE FOR CONTINUOUS ELECTROFORMING OF METAL FOIL	16-Jul-1985
4543270	METHOD FOR DEPOSITING A MICRON-SIZE METALLIC FILM ON A TRANSPARENT SUBSTRATE UTILIZING A VISIBLE LASER	24-Sep-1985
4568413	METALLIZED AND PLATED LAMINATES	04-Feb-1986
4592975	METHOD FOR REPAIRING A PHOTOMASK BY LASER-INDUCED POLYMER DEGRADATION	03-Jun-1986
4606932	METHOD FOR DEPOSITING A MICRON-SIZE METALLIC FILM ON A TRANSPARENT SUBSTRATE UTILIZING A VISIBLE LASER	19-Aug-1986
4692221	IN-SITU DENDRITIC TREATMENT OF ELECTRODEPOSITED FOIL	08-Sep-1987
4727234	LASER-BASED SYSTEM FOR THE TOTAL REPAIR OF PHOTOMASKS	23-Feb-1988
4789438	CATHODE SURFACE TREATMENT FOR ELECTROFORMING METALLIC FOIL OR STRIP	06-Dec-1988
4863808	COPPER-CHROMIUM-POLYIMIDE COMPOSITE	05-Sep-1989
4875283	METHOD AND APPARATUS FOR MANUFACTURING PRINTED CIRCUIT BOARDS	24-Oct-1989
4898647	PROCESS AND APPARATUS FOR ELECTROPLATING COPPER FOIL	06-Feb-1990
4956053	APPARATUS AND PROCESS FOR THE PRODUCTION OF MICRO-PORE FREE HIGH DUCTILITY METAL FOIL	11-Sep-1990
5017271	METHOD FOR PRINTED CIRCUIT BOARD PATTERN MAKING USING SELECTIVELY ETCHABLE METAL LAYERS	21-May-1991
5057372	MULTILAYER FILM AND LAMINATE FOR USE IN PRODUCING PRINTED CIRCUIT BOARDS	15-Oct-1991
5066366	METHOD FOR MAKING FOIL	19-Nov-1991

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Thursday, September 18, 2003

**TRADEMARK**  
**REEL: 002725 FRAME: 0111**

5120590	PROTECTED CONDUCTIVE FOIL AND PROCEDURE	09-Jun-1992
5153050	COMPONENT OF PRINTED CIRCUIT BOARDS	06-Oct-1992
5167997	PROTECTED CONDUCTIVE FOIL AND PROCEDURE	01-Dec-1992
5171417	ELECTRODEPOSITED FOIL WITH CONTROLLED PROPERTIES FOR PRINTED CIRCUIT BOARD APPLICATIONS AND PROCEDURES AND ELECTROLYTE BATH SOLUTIONS FOR PREPARING THE SAME	15-Dec-1992
5181770	SURFACE TOPOGRAPHY OPTIMIZATION THROUGH CONTROL OF CHLORIDE CONCENTRATION IN ELECTROFORMED COPPER FOIL	26-Jan-1993
5215645	ELECTRODEPOSITED FOIL WITH CONTROLLED PROPERTIES FOR PRINTED CIRCUIT BOARD APPLICATIONS AND PROCEDURES AND ELECTROLYTE BATH SOLUTIONS FOR PREPARING THE SAME	01-Jun-1993
5228965	METHOD AND APPARATUS FOR APPLYING SURFACE TREATMENT TO METAL FOIL	20-Jul-1993
5242562	METHOD AND APPARATUS FOR FORMING PRINTED CIRCUITS	07-Sep-1993
5256474	METHOD AND APPARATUS FOR MANUFACTURING PRINTED CIRCUIT BOARDS	26-Oct-1993
5322975	UNIVERSAL CARRIER SUPPORTED THIN COPPER LINE	21-Jun-1994
5332486	ANTI-OXIDANT COATINGS FOR COPPER FOILS	26-Jul-1994
5344538	THIN PLATE ANODE	06-Sep-1994
5350487	METHOD OF ETCHING POLYIMIDE	27-Sep-1994
5366612	PROCESS FOR MAKING COPPER FOIL	22-Nov-1994
5372297	DRUM CATHODE FOR USE IN THE PRODUCTION OF METAL FOILS AND A METHOD OF PRODUCING THE SAME	13-Dec-1994
5393396	APPARATUS FOR ELECTRODEPOSITING METAL	28-Feb-1995
5403465	ELECTRODEPOSITED COPPER FOIL AND PROCESS FOR MAKING SOLUTIONS HAVING LOW CHLORIDE ION CONCENTRATIONS	04-Apr-1995



5421985	ELECTRODEPOSITED COPPER FOIL AND PROCESS FOR MAKING SOLUTIONS HAVING LOW CHLORIDE ION CONCENTRATIONS	06-Jun-1995
5429738	METHOD AND APPARATUS FOR FORMING PRINTED CIRCUITS	04-Jul-1995
5431803	ELECTRODEPOSITED COPPER FOIL AND PROCESS FOR MAKING SOLUTIONS HAVING LOW CHLORIDE ION CONCENTRATIONS	11-Jul-1995
5454926	ELECTRODEPOSITED COPPER FOIL AND PROCESS FOR MAKING SOLUTIONS HAVING LOW CHLORIDE ION CONCENTRATIONS	03-Oct-1995
5458746	PROCESS FOR MAKING COPPER METAL POWDER, COPPER OXIDES AND COPPER FOIL	17-Oct-1995
5525433	EPOXY ADHESIVES AND COPPER FOILS AND COPPER CLAD LAMINATES USING SAME	11-Jun-1996
5614324	MULTI-LAYER STRUCTURES CONTAINING A SILANE ADHESION PROMOTING LAYER	25-Mar-1997
5622782	FOIL WITH ADHESION PROMOTING LAYER DERIVED FROM SILANE MIXTURE	22-Apr-1997
5629098	EPOXY ADHESIVES AND COPPER FOILS AND COPPER CLAD LAMINATES USING SAME	13-May-1997
5670033	PROCESS FOR MAKING COPPER METAL POWDER, COPPER OXIDES AND COPPER FOIL	23-Sep-1997
5674596	COMPONENT OF PRINTED CIRCUIT BOARDS	07-Oct-1997
5679232	PROCESS FOR MAKING WIRE	21-Oct-1997
5681443	METHOD AND APPARATUS FOR SEQUENTIALLY METALIZING POLYMERIC FILMS AND PRODUCTS MADE THEREBY	28-Oct-1997
5685970	METHOD AND APPARATUS FOR SEQUENTIALLY METALIZING POLYMERIC FILMS AND PRODUCTS MADE THEREBY	11-Nov-1997
5709957	METALLIC BODY WITH VAPOR-DEPOSITED TREATMENT LAYER(S) AND ADHESION-PROMOTING LAYER	20-Jan-1998
5716502	METHOD AND APPARATUS FOR SEQUENTIALLY METALIZING POLYMERIC FILMS AND PRODUCTS MADE THEREBY	10-Feb-1998

5725937	COMPONENT OF PRINTED CIRCUIT BOARDS	10-Mar-1998
5762778	NON-CYANIDE BRASS PLATING BATH AND METHOD OF MAKING METALLIC FOIL HAVING A BRASS LAYER USING THE NON-CYANIDE BRASS PLATING BATH	09-Jun-1998
5840170	METHOD FOR INHIBITING THE ELECTRODEPOSITION OF ORGANIC PARTICULATE MATTER ON COPPER FOIL	24-Nov-1998
5863666	HIGH PERFORMANCE ELECTRODEPOSITED FOILS FOR FATIGUE APPLICATIONS	26-Jan-1999
5885436	ADHESION ENHANCEMENT FOR METAL FOIL	23-Mar-1999
5908542	METAL FOIL WITH IMPROVED BONDING TO SUBSTRATES AND METHOD FOR MAKING SAID FOIL	01-Jun-1999
5908544	IMPROVED ZINC CHROMIUM STABILIZER CONTAINING A HYDROGEN INHIBITING ADDITIVE	01-Jun-1999
5942315	COMPONENT OF PRINTED CIRCUIT BOARDS	24-Aug-1999
5944965	METHOD AND APPARATUS FOR SEQUENTIALLY METALIZING POLYMERIC FILMS AND PRODUCTS MADE THEREBY	31-Aug-1999
5951803	COMPONENT OF PRINTED CIRCUIT BOARDS	14-Sep-1999
6042711	NICKEL FLASH ON HIGH PROFILE COPPER TREATMENT	28-Mar-2000
6048430	COMPONENT OF PRINTED CIRCUIT BOARDS	11-Apr-2000
6086743	ADHESION ENHANCEMENT FOR METAL FOIL	11-Jul-2000
6103135	MULTI-LAYER LAMINATE AND METHOD OF PRODUCING SAME	15-Aug-2000
6117536	AN ADHESION PROMOTING LAYER FOR USE WITH EPOXY PREPREGS	12-Sep-2000
6132589	TREATMENT FOR NON DICY CONTAINING LAMINATES USING A ZINC OXIDE LAYER	17-Oct-2000
6132851	ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD LAMINATES USING SAME	17-Oct-2000
6132887	HIGH FATIGUE DUCTILITY ELECTRODEPOSITED COPPER FOIL	17-Oct-2000

6146480	FLEXIBLE LAMINATE FOR FLEXIBLE CIRCUIT	14-Nov-2000
6168703	IMPROVED ZINC CHROMIUM STABILIZER CONTAINING A HYDROGEN INHIBITING ADDITIVE	02-Jan-2001
6171714	ADHESIVELESS FLEXIBLE LAMINATE AND PROCESS FOR MAKING ADHESIVELESS FLEXIBLE LAMINATE	09-Jan-2001
6183607	ANODE STRUCTURE FOR MANUFACTURE OF METALLIC FOIL	06-Feb-2001
6221176	SURFACE TREATMENT OF COPPER FOR FLEXIBLE CIRCUITS	24-Apr-2001
6224722	METHOD AND APPARATUS FOR SEQUENTIALLY METALIZING POLYMERIC FILMS AND PRODUCTS MADE THEREBY	01-May-2001
6224951	FLEXIBLE LAMINATE FOR FLEXIBLE CIRCUIT	01-May-2001
6238778	COMPONENT OF PRINTED CIRCUIT BOARDS	29-May-2001
6248401	METALLIC BODY WITH VAPOR-DEPOSITED TREATMENT LAYER(S) AND ADHESION- PROMOTING LAYER	19-Jun-2001
6268070	LAMINATE FOR MULTI-LAYER PRINTED CIRCUIT	31-Jul-2001
6284982	METHOD AND COMPONENT FOR FORMING AN EMBEDDED RESISTOR IN A MULTI-LAYER PRINTED CIRCUIT	04-Sep-2001
6296949	COPPER COATED POLYIMIDE WITH METALLIC PROTECTIVE LAYER	02-Oct-2001
6299721	COATINGS FOR IMPROVED RESIN DUST RESISTANCE	09-Oct-2001
6316733	COMPONENT FOR USE IN FORMING PRINTED CIRCUIT BOARDS (lattice)	13-Nov-2001
6341698	SHEET STACKING DEVICE	29-Jan-2002
6361673	ELECTROFORMING CELL	26-Mar-2002
6376008	RESIN/COPPER/METAL LAMINATE AND METHOD OF PRODUCING SAME	23-Apr-2002
6379487	COMPONENT OF PRINTED CIRCUIT BOARD	30-Apr-2002
6426146	TREATMENT FOR NON DICY CONTAINING LAMINATES USING A ZINC OXIDE LAYER	30-Jul-2002

6447929	THIN COPPER ON USABLE CARRIER AND METHOD OF FORMING SAME	10-Sep-2002
6489034	METHOD OF FORMING CHROMIUM COATED COPPER FOR PRINTED CIRCUIT BOARDS	03-Dec-2002
6489035	METHOD OF FORMING CHROMIUM COATED COPPER FOR PRINTED CIRCUIT BOARDS	03-Dec-2002
6537675	COATINGS FOR IMPROVED RESIN DUST RESISTANCE	25-Mar-2003
6589381	COATINGS FOR IMPROVED RESIN DUST RESISTANCE	08-Jul-2003
6589413	METHOD OF MAKING A COPPER ON INVAR COMPOSITE	08-Jul-2003
6622374	RESISTOR COMPONENT WITH MULTIPLE LAYERS OF RESISTIVE MATERIAL	23-Sep-2003

## Gould Electronics Inc. U.S. Trademarks

Country: United States of America					
Mark	Class(es)	Appln No.	Filing Date	Reg. No.	Reg. Date
CAC	9	74/363129	23-Feb-93	1800591	26-Oct-93
design logo	6, 9	75/641616	12-Feb-99	2368020	18-Jul-00
design logo	9	73/385091	13-Sep-82	1267714	21-Feb-84
DUOFOIL	6	73/702716	24-Dec-87	1519518	10-Jan-89
GOULD	7, 9, 10	73/385090	13-Sep-82	1271536	27-Mar-84
GOULD	9	72/003180	23-Feb-56	635119	02-Oct-56
GOULD	6, 9	75/641617	12-Feb-99	2376973	15-Aug-00
GOULD	9	75/200229	19-Nov-96	2127029	06-Jan-98
GOULD & design logo	9, 10	73/493699	06-Aug-84	1356346	27-Aug-85
GOULD & design logo	9, 10	73/028140	30-Jul-74	1020371	16-Sep-75
GOULD.COM	42	75/784594	25-Aug-99	2556738	02-Apr-02
TCC	17	76/320028	01-Oct-01	2687406	11-Feb-03
TCC & design	17	76/320027	01-Oct-01	2687405	11-Feb-03
TCR	6	76/320026	01-Oct-01	2687404	11-Feb-03
TCR & design	6	76/320025	01-Oct-01	2687403	11-Feb-03
TCU	6	78/105362	29-Jan-02	2762872	09-Sep-03